DSA8004 (Tentative)

Silicon PNP epitaxial planar type

For low frequency output amplification

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	–60	V
Collector-emitter voltage (Base open)	V_{CEO}	–50	V
Emitter-base voltage (Collector open)	V_{EBO}	–5	V
Collector current	I_C	–2	A
Peak collector current	I_{CP}	–3	A
Collector power dissipation *	P_C	1	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C

Note) *: Printed circuit board: Copper foil area of 1 cm^2 or more, and the board thickness of 1.7 mm for the collector portion

■ Package

- Code
  MT-2-A1-B
- Pin Name
  1. Emitter
  2. Collector
  3. Base

■ Marking Symbol: 4B

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = –10\ \mu A$, $I_E = 0$	–60			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = –1$ mA, $I_B = 0$	–50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = –10\ \mu A$, $I_C = 0$	–5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = –20$ V, $I_E = 0$			– 0.1	μA
Forward current transfer ratio *1	h_{FE1} *2	$V_{CE} = –2$ V, $I_C = –200$ mA	120		340	—
	h_{FE2}	$V_{CE} = –2$ V, $I_C = –1$ A	60			
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_C = –1$ A, $I_B = –50$ mA		– 0.2	– 0.3	V
Base-emitter saturation voltage *1	$V_{BE(sat)}$	$I_C = –1$ A, $I_B = –50$ mA		– 0.9	–1.2	V
Transition frequency	f_T	$V_{CE} = –10$ V, $I_C = –50$ mA		130		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = –10$ V, $I_E = 0$, f = 1 MHz		33	60	pF

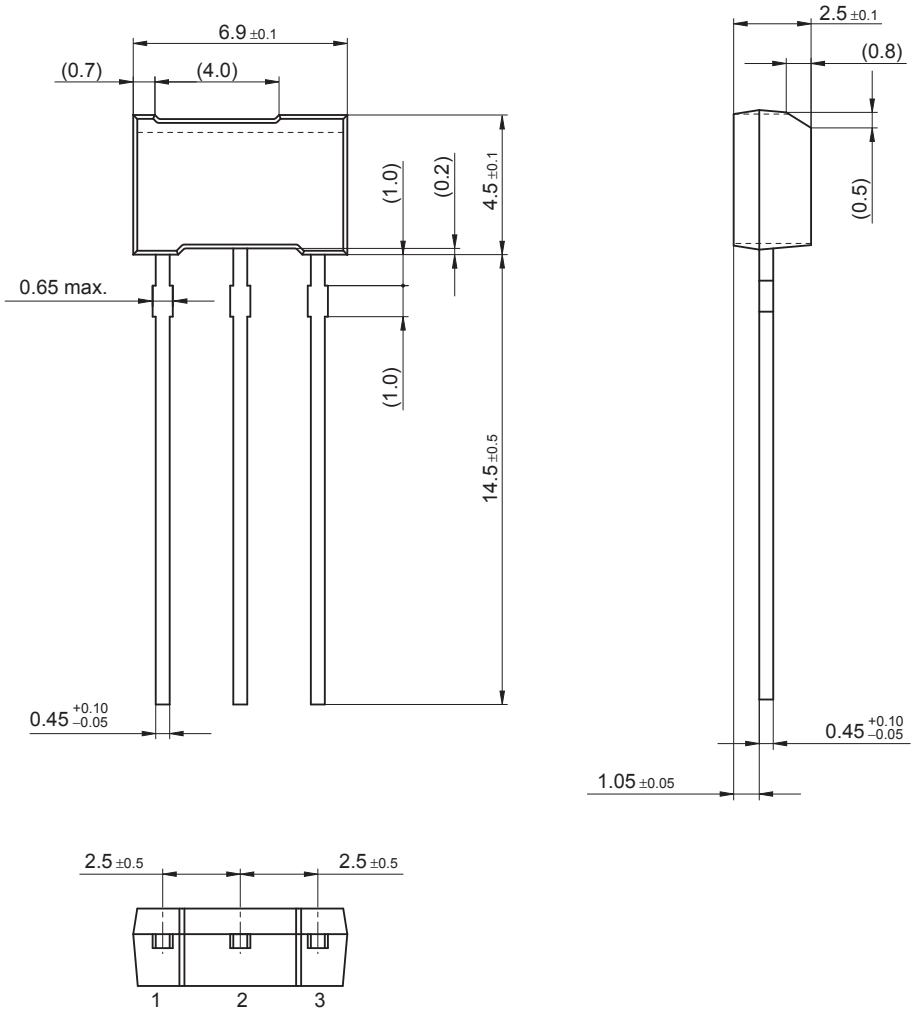
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *1: Pulse measurement
*2: Rank classification

Code	R	S	0
Rank	R	S	No-rank
h_{FE1}	120 to 240	170 to 340	120 to 340
Marking Symbol	4BR	4BS	4B

Product of no-rank is not classified and have no marking symbol for rank.

MT-2-A1-B

Unit: mm



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